



Parameter	Rating	Units
Blocking Voltage	100	V _P
Load Current	350	mA _{rms} / mA _{DC}
On-Resistance (max)	3	Ω

Features

- 3750V_{rms} Input/Output Isolation
- Low Drive Power Requirements
- High Reliability
- Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation
- Small 6-Pin Package
- Surface Mount Tape & Reel Version Available
- Flammability Rating UL 94 V-0

Applications

- Instrumentation
- Multiplexers
- Data Acquisition
- Electronic Switching
- I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment—Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Description

The PLA134 is a single-pole, normally open (1-Form-A) Solid State Relay that uses optically coupled MOSFET technology to provide 3750V_{rms} of input-to-output isolation. With its combination of low on-resistance and high load current handling, the PLA134 is suitable for a variety of industrial applications.

Its optically coupled outputs, which use the patented OptoMOS architecture, are controlled by a highly efficient infrared LED.

Because Solid State Relays have no moving parts, they can offer faster, bounce-free switching in a more compact surface mount or through hole package than traditional electromechanical relays.

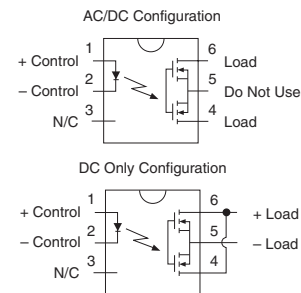
Approvals

- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1175739
- EN/IEC 60950-1 Certified Component:
Certificate available on our website

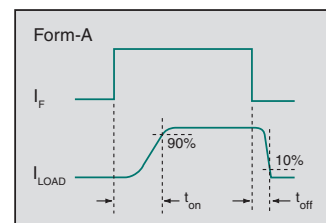
Ordering Information

Part Number	Description
PLA134	6-Pin DIP (50/Tube)
PLA134S	6-Pin Surface Mount (50/Tube)
PLA134STR	6-Pin Surface Mount (1,000/Reel)

Pin Configuration



Switching Characteristics of Normally Open Devices



Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Blocking Voltage	100	V _p
Reverse Input Voltage	5	V
Input Control Current	50	mA
Peak (10ms)	1	A
Input Power Dissipation ¹	150	mW
Total Power Dissipation ²	800	mW
Isolation Voltage, Input to Output	3750	V _{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

¹ Derate linearly 1.33 mW / °C

² Derate linearly 6.67 mW / °C

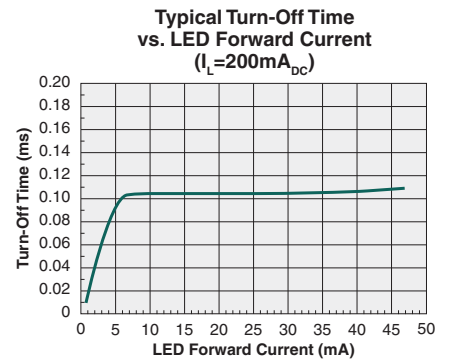
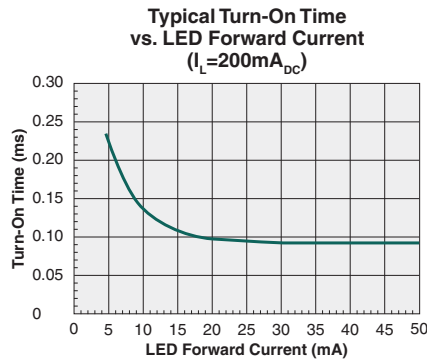
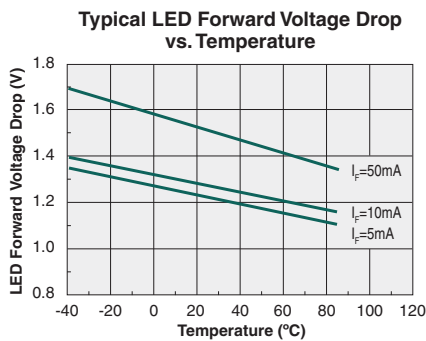
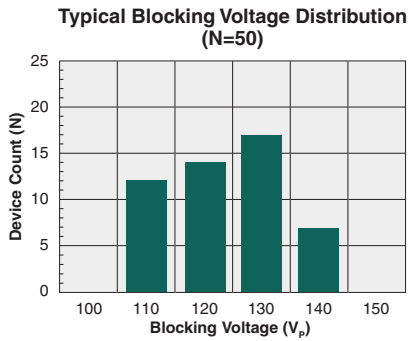
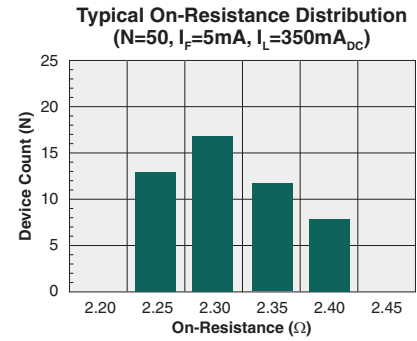
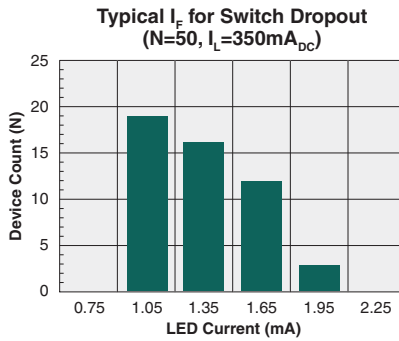
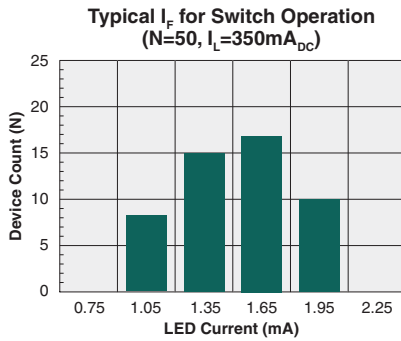
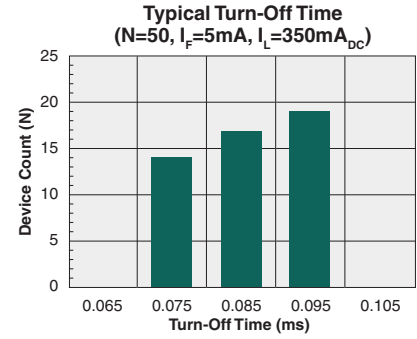
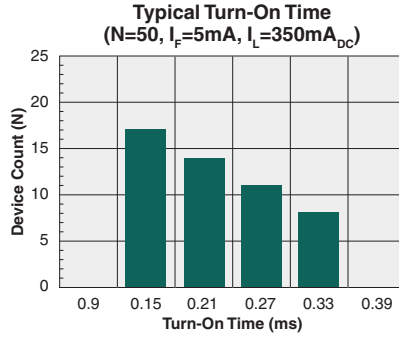
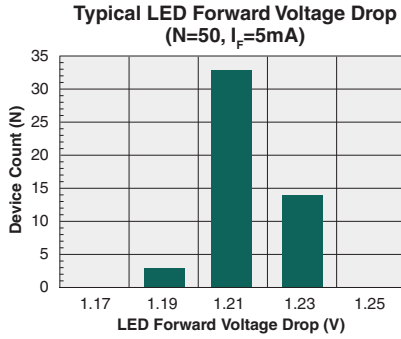
Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

Electrical Characteristics @ 25°C

Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Load Current (Continuous)						
AC/DC Configuration	-	I _L	-	-	350	mA _{rms} / mA _{DC}
DC Configuration			-	-	750	mA _{DC}
Peak Load Current	t=10ms	I _{LPK}	-	-	±1	mA _p
On-Resistance						
AC/DC Configuration	I _F =350mA	R _{ON}	-	-	3	Ω
DC Configuration	I _F =750mA		-	-	0.8	
Off-State Leakage Current	V _L =100V _p	I _{LEAK}	-	-	1	μA
Switching Speeds						
Turn-On	I _F =5mA, I _L =10mA	t _{on}	-	-	5	ms
Turn-Off		t _{off}				
Input Characteristics						
Input Control Current to Activate	I _L =350mA	I _F	-	-	5	mA
Input Control Current to Deactivate	-	I _F	0.4	-	-	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.2	1.5	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μA
Common Characteristics						
Capacitance, Input to Output	V _{IO} =0V, f=1MHz	C _{IO}	-	3	-	pF

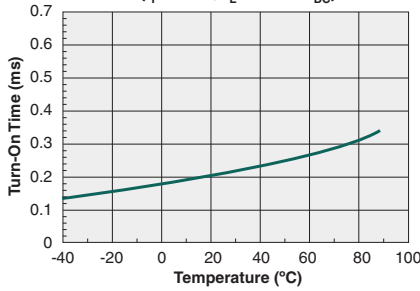
PERFORMANCE DATA*



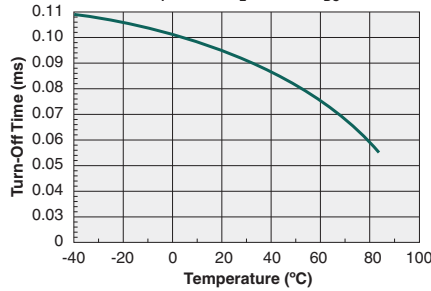
*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C. For guaranteed parameters not indicated in the written specifications, please contact our application department.

PERFORMANCE DATA*

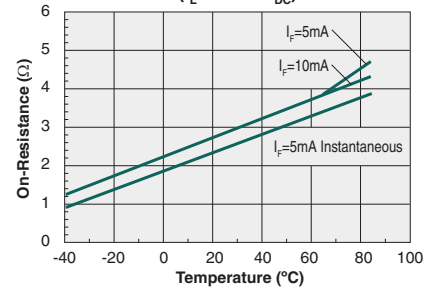
Typical Turn-On Time vs. Temperature
($I_F=5\text{mA}$, $I_L=200\text{mA}_{\text{DC}}$)



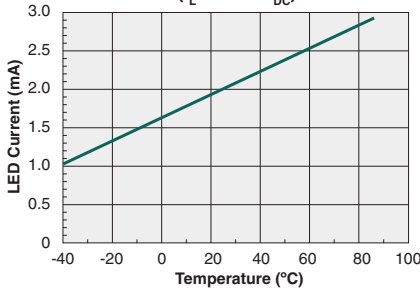
Typical Turn-Off Time vs. Temperature
($I_F=5\text{mA}$, $I_L=200\text{mA}_{\text{DC}}$)



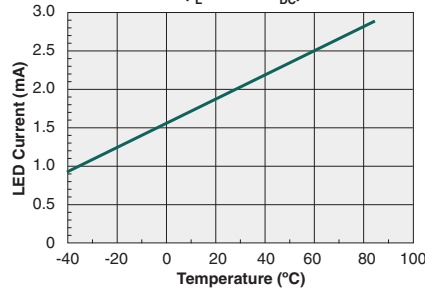
Typical On-Resistance vs. Temperature AC/DC Configuration
($I_L=350\text{mA}_{\text{DC}}$)



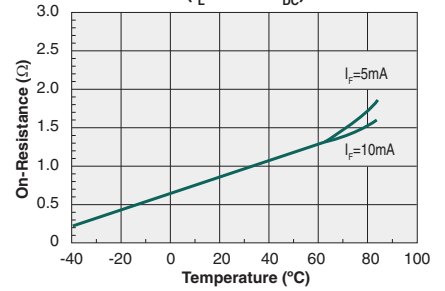
Typical I_F for Switch Operation vs. Temperature
($I_L=200\text{mA}_{\text{DC}}$)



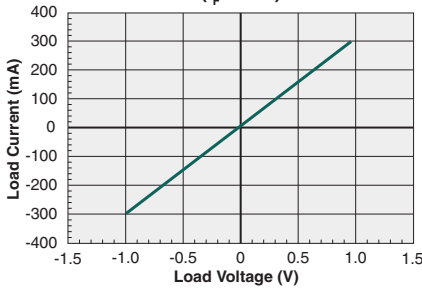
Typical I_F for Switch Dropout vs. Temperature
($I_L=200\text{mA}_{\text{DC}}$)



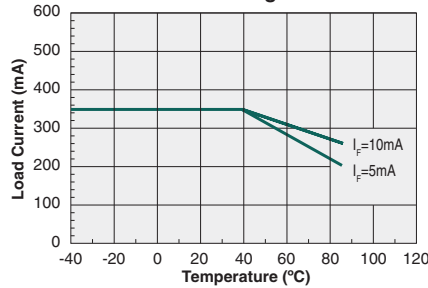
Typical On-Resistance vs. Temperature DC-Only Configuration
($I_L=350\text{mA}_{\text{DC}}$)



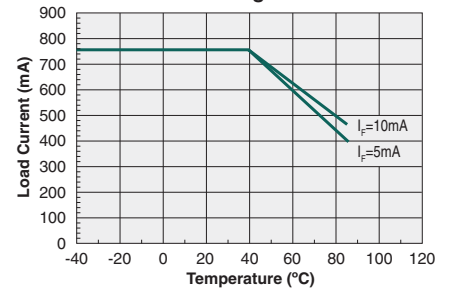
Typical Load Current vs. Load Voltage
($I_F=5\text{mA}$)



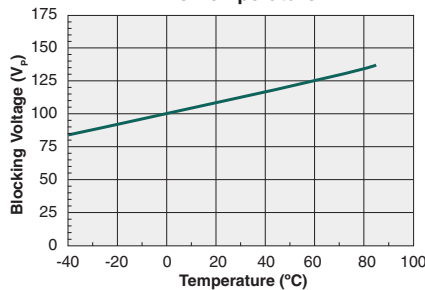
Maximum Load Current vs. Temperature AC/DC Configuration



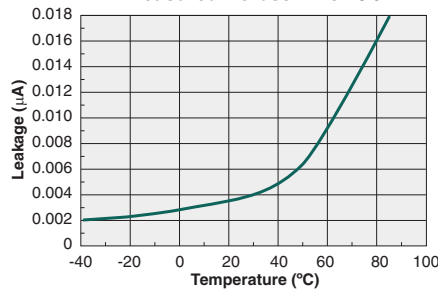
Maximum Load Current vs. Temperature DC Configuration



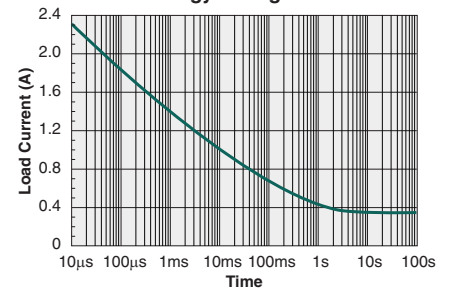
Typical Blocking Voltage vs. Temperature



Typical Leakage vs. Temperature Measured Across Pins 4&6



Energy Rating Curve



*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C.
For guaranteed parameters not indicated in the written specifications, please contact our application department.

Manufacturing Information

Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a Moisture Sensitivity Level (MSL) classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Classification
PLA134 / PLA134S	MSL 1

ESD Sensitivity



This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Soldering Profile

Provided in the table below is the Classification Temperature (T_C) of this product and the maximum dwell time the body temperature of this device may be ($T_C - 5$)°C or greater. The classification temperature sets the Maximum Body Temperature allowed for this device during lead-free reflow processes. For through-hole devices, and any other processes, the guidelines of **J-STD-020** must be observed.

Device	Classification Temperature (T_C)	Dwell Time (t_p)	Max Reflow Cycles
PLA134	250°C	30 seconds	1
PLA134S	250°C	30 seconds	3

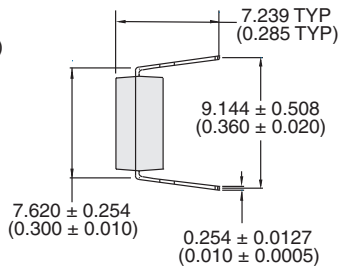
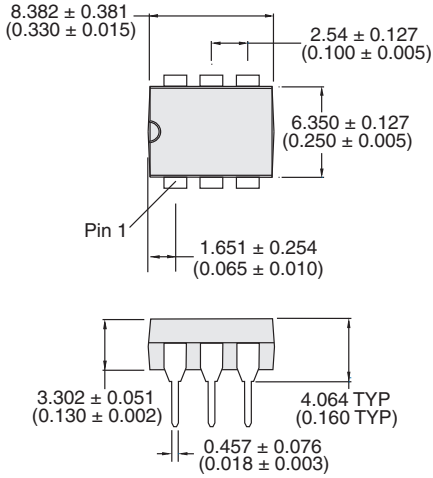
Board Wash

IXYS Integrated Circuits recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include, but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to flux or solvents that are Chlorine- or Fluorine-based.

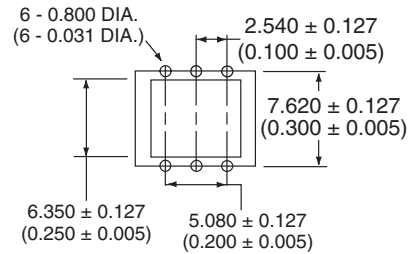


Mechanical Dimensions

PLA134

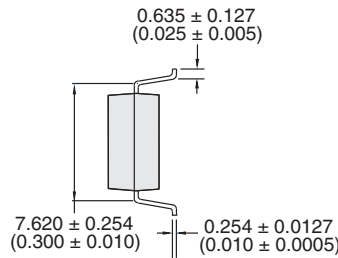
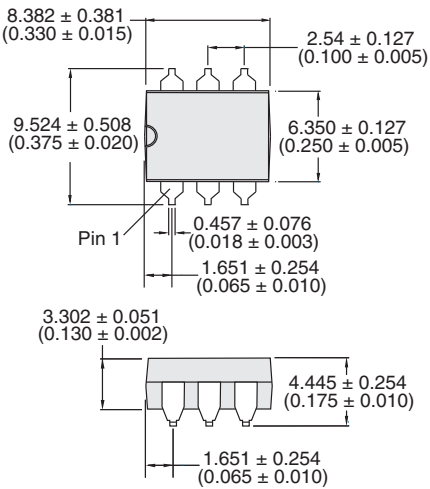


PCB Hole Pattern

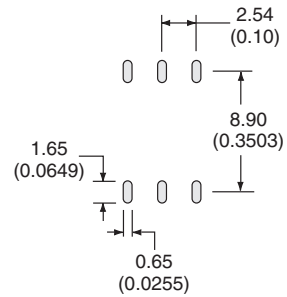


Dimensions
mm
(inches)

PLA134S

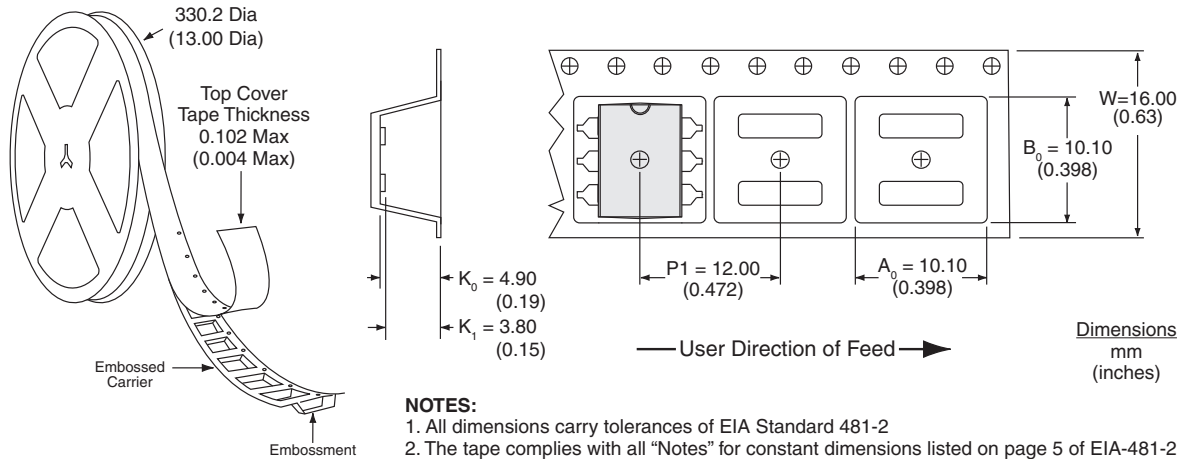


PCB Land Pattern



Dimensions
mm
(inches)

PLA134STR Tape & Reel



For additional information please visit our website at: www.ixysic.com

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